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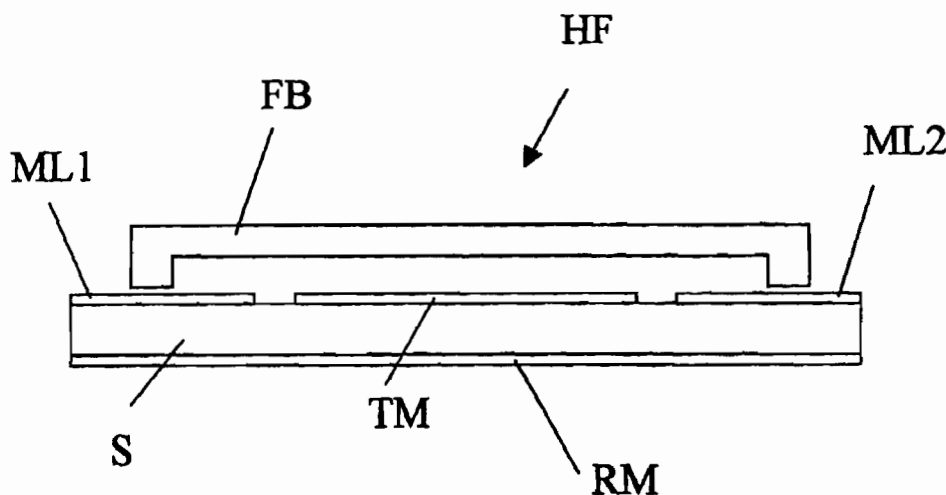
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(54) Title: WAVEGUIDE FILTER

(54) Bezeichnung: HOHLLEITERFILTER



(57) Abstract: The invention relates to a waveguide filter comprised of a metallic layer (TM), which is structured on the top side, of a substrate (S), which is coated with one or more metallic striplines (ML1, ML2), and of a component (FB). Said component (FB) is placed on the top side of the substrate (S). One sidewall of the waveguide filter is formed by the structured metallic layer (TM) of the substrate (S), whereby the remaining sidewalls of the waveguide filter are formed by the component (FB). The waveguide filter has launching and extraction points for launching the electromagnetic wave, which is guided inside the stripline (ML1, ML2), into the waveguide filter and vice versa.

(57) Zusammenfassung: Die Erfindung betrifft ein Hohlleiterfilter gebildet aus einem auf der Oberseite mit einer strukturierten metallischen Schicht (TM) und ein oder mehreren metallischen Streifenleitungen (ML1, ML2) beschichteten Substrat (S) und einem Bauteil (FB), wobei das Bauteil (FB) auf der Oberseite des Substrats (S) aufgebracht ist und wobei eine Seitenwand des Hohlleiterfilters durch die strukturierte metallische Schicht (TM) des Substrats (S) und die übrigen Seitenwände des Hohlleiterfilters durch das Bauteil (FB) gebildet werden und wobei das Hohlleiterfilter Ein- und Auskoppelstellen zur Kopplung der in der Streifenleitung (ML1, ML2) geführten elektromagnetischen Welle in das Hohlleiterfilter und umgekehrt aufweist.



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Zur Erklärung der Zweibuchstaben-Codes und der anderen Abkürzungen wird auf die Erklärungen ("Guidance Notes on Codes and Abbreviations") am Anfang jeder regulären Ausgabe der PCT-Gazette verwiesen.

Waveguide filter

The invention relates to a waveguide filter as claimed in patent claim 1.

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Waveguide filters are conventional components for microwave and millimetric wave technology. This filter type normally has relatively high resonator Q-factors and narrow electrical tolerances for the passband and cutoff band. Waveguide filters are distinguished by high stop-band attenuations and a low insertion loss. Waveguide filters are preferably used where it is no longer possible to use planar filters owing to stringent requirements for the electrical tolerance accuracy and the Q-factor.

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An arrangement for frequency-selective suppression of radio-frequency signals is known from DE 197 57 892 A1. The arrangement in this case has a baseplate with a first and a second substrate surface, each having a coupling connection and each having an electrically conductive panel. A shroud which is arranged over the baseplate, together with the electrically conductive panel, forms a hollow chamber which acts as a cavity resonator. The cavity resonator acts as a high-pass filter, so that the only frequencies which can propagate are those which are higher than a cutoff frequency that is determined by the geometric dimensions of the cavity resonator.

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A further known filter is known from US 6,236,291 B1. A housing which, together with the upper face of the substrate, forms a cavity is arranged on the upper face of a substrate whose lower face is completely metallically coated. A dielectric panel which acts as a dielectric filter is arranged in this cavity.

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Figure 1 shows a further possible arrangement. The illustration shows the integration of a waveguide filter in a planar circuit according to the prior art. The arrangement comprises a substrate S which has a first stripline ML1 and a second stripline ML2, for example a microstripline, on the upper face. The first stripline ML1 is in this case used for inputting the transported electromagnetic wave into the waveguide filter HF, and the second stripline ML2 is used for outputting the wave from the waveguide filter HF. Input and output points are provided at the two ends of the filter for inputting/outputting the signal from/to the stripline, in order to change the signal from the mode which can propagate on the stripline to the waveguide mode which can propagate in the filter, and vice versa.

These coupling points are formed at both ends of the filter from the striplines ML1, ML2, the substrate S, the shielding-cap SC, the via holes VH, the rear aperture face body RM and the baseplate TP with the cap DB.

The striplines ML1, ML2 each end underneath a shielding SC, which is used to prevent radiated emission of electromagnetic waves to the surrounding area. Rear-face metallization RM, which has an aperture DB in the area of the shielding cap, is located on the lower face of the substrate S. A metallic baseplate TP is arranged on the lower face of the substrate and likewise has an aperture DB in the area of the shielding cap, so that the two apertures in the rear-face metallization of the substrate and in the baseplate TP are aligned with one another. The waveguide filter HF is screwed to this baseplate TP, with each of the openings in the waveguide filter being connected to the apertures DB.

An electromagnetic wave passes from the first stripline ML1 through the substrate S and the aperture DB into the waveguide filter HF. The electromagnetic wave is

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then passed from the waveguide filter HF through the apertures DB to the second stripline ML2.

One disadvantage of the integration of a conventional waveguide filter in a stripline environment (for example on printed circuits) is the high costs associated with this which, until now, have prevented widespread use of this principle. The cost drivers in this area are the large number of manufacturing steps and components, and the necessity to fit components on the front face and rear face of the substrate.

The waveguide junction requires a precision-manufactured, mechanically accurately positioned shielding cap SC. The metallization on both faces of the substrate S must be structured with a small offset between the conductor track patterns on the lower face and upper face. The aperture DB in the baseplate must be produced in an additional manufacturing step. The substrate S must be connected to the baseplate TP conductively and accurately positioned. A shielding cap, which must be produced as a separate component, must be fitted to the substrate S conductively and accurately positioned.

The waveguide filter HF normally comprises two parts (a waveguide filter lower part with three side walls of the waveguide filter and a cover part as a fourth side wall of the waveguide filter) which must be produced separately and must first of all be joined. The joined filter must then be attached to the lower face of the baseplate, such that it is accurately positioned.

Further disadvantages result from the fact that the waveguide filter normally has a number of components (shielding cap, baseplate, waveguide filter) and that this type of implementation occupies a large amount of space.

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The object of the invention is thus to provide a waveguide filter which can be adapted to a printed circuit board easily, at low cost and in a space-saving manner.

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This object is achieved by the waveguide filter as claimed in the features of patent claim 1. Advantageous embodiments of the waveguide filter according to the invention are the subject matter of dependent claims.

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According to the invention, the waveguide filter is formed from a substrate, which is coated on the upper face with a structured metallic layer and one or more metallic striplines, and from a component, with the component being fitted to the upper face of the substrate and with one side wall of the waveguide filter being formed by the structured metallic layer of the substrate, and with the other side walls of the waveguide filter being formed by the component, and with the waveguide filter having input and output points for coupling the electromagnetic waves carried in the stripline to the waveguide filter, and vice versa.

25 One advantage of the invention is that the waveguide filter according to the invention essentially comprises a single component which can be produced easily and at low cost and is fitted to the upper face of an appropriately previously structured substrate. The waveguide filter is in this case not formed by the component or the substrate per se, but only by the arrangement of the two elements with respect to one another according to the invention.

35 The component can advantageously be a surface mounted device. A large number of the components used on a printed circuit board are normally surface mounted devices. The waveguide filter surface mounted device according to the invention can expediently be included

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in the manufacturing process. The assembly can be populated from just one side. This results in further advantages in terms of manufacturing costs and time.

5 The component, which is also referred to as the filter upper part, advantageously has a conductive surface and may, for example, be produced from metal or metallized plastic, with the latter resulting in further advantages in terms of production costs and weight. The
10 filter upper part is advantageously conductively connected to the substrate, in particular with the filter upper part being soldered or conductively adhesively bonded to the substrate.

15 In one advantageous embodiment of the invention, the filter upper part is structured on that side wall which is opposite the upper face of the substrate (that is to say the substrate face to which the filter upper part is attached). This structure can in this case be
20 predetermined, depending on the desired waveguide filter characteristics. The cross section of the waveguide filter can advantageously be chosen to correspond to the radio-frequency signal to be filtered.

25 The invention as well as further advantageous embodiments will be explained in more detail in the following text with reference to drawings, in which:

30 Figure 1 shows a waveguide filter, fitted to a substrate, according to the prior art,

Figure 2 shows a plan view of the filter upper part with a structured internal surface,

35 Figure 3 shows a longitudinal section through the filter upper part along the section line A-A' in Figure 2,

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Figure 4 shows a plan view of the metallized layer on the upper face of the substrate, and

5 Figure 5 shows a cross section through an arrangement according to the invention of a waveguide filter comprising a substrate and a filter upper part, along the section line B-B' in Figure 2 and Figure 4.

10 Figure 2 shows a plan view of the filter upper part with a structured inner surface. At each of its opposite ends, the filter upper part FB has an opening OZ through which the microstriplines (see Figure 4 and Figure 5) are passed into the waveguide filter. The
15 filter upper part FB is essentially U-shaped (see Figure 3) and has a structure SK in the interior. The structure SK is in this case advantageously chosen to correspond to the desired waveguide filter characteristics.

20 Manufacturing methods such as milling or plastic injection molding can be used to produce mechanically high-precision structures SK, so that the waveguide filter also, in a corresponding manner, has only minor
25 electrical tolerances for the input and filter function.

Furthermore, the filter upper part FB advantageously has a circumferential web ST (Figure 2 and Figure 3).
30 In the waveguide filter, this web ST is seated directly on the metallized upper face of the substrate (not shown). This web ST is expediently adapted for the respective joining method that is used. The conductive solder or the conductive adhesive can be distributed in
35 the space formed between the filter upper part and the substrate when they are joined together, thus ensuring an optimum connection.

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The web ST can expediently be adapted such that, for example when the joining method is "soldering", the surface tensions which occur in the solder during the soldering process can be used to ensure that the component FB is positioned exactly on the metallically structured layer illustrated in Figure 4 during the soldering process.

Figure 3 shows a section illustration of the filter upper part along the section line A-A' in Figure 2. The illustration shows the essentially U-shaped filter upper part FB with the internal structure SK. The structure SK is in this case illustrated only by way of example. Other structure forms are, of course, also possible depending on the application.

Figure 4 shows a plan view of the metallized upper face of the substrate, to which the filter upper part can be fitted in order to form the waveguide filter according to the invention. In this case, ML1, ML2 denote the striplines, and TM denotes the metallization, which forms one wall of the waveguide filter in the arrangement according to the invention. The striplines ML1, ML2 may, for example, be microstriplines and are used for inputting and outputting the electromagnetic waves into and out of the waveguide filter.

Figure 5 shows a section illustration along the section line B-B' from Figure 2 and Figure 4 for a waveguide filter arrangement according to the invention. The waveguide filter HF is formed by the filter upper part FB, as illustrated in Figure 2, being fitted with high-precision to the metallized upper face TM of the substrate S, as illustrated in Figure 4.

The striplines ML1, ML2 which are formed on the upper face of the substrate S lead from the outside into the internal area of the waveguide filter HF. The metallization TM on the upper face of the substrate S

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forms the fourth wall, according to the invention, of the waveguide filter HF. The other side walls (not illustrated) of the waveguide filter HF are formed by the filter upper part FB.

Patent Claims

1. A waveguide filter formed from a substrate (S), which is coated on the upper face with a structured metallic layer (TM) and one or more metallic striplines (ML1, ML2), and from a component (FB), with the component (FB) being fitted to the upper face of the substrate (S) and with one side wall of the waveguide filter being formed by the structured metallic layer (TM) of the substrate (S), and with the other side walls of the waveguide filter being formed by the component (FB), and with the waveguide filter having input and output points for coupling the electromagnetic waves carried in the stripline (ML1, ML2) to the waveguide filter, and vice versa, and with that side wall of the component (S) which is opposite the upper face of the substrate (S) has a structure (SK), characterised in that the component has a web (ST) which rests on the structured metallic layer (TM) on the upper face of the substrate (S) and which follows the structure (SK).

2. The waveguide filter as claimed in claim 1, characterized in that the component (FB) is a surface mounted device.

3. The waveguide filter as claimed in one of the preceding claims, characterized in that the cross section of the component (FB) is chosen in accordance with the predeterminable filter characteristics of the waveguide filter (HF).

4. The waveguide filter as claimed in one of the preceding claims, characterized in that the at least one stripline (ML1, ML2) which is provided on the upper face of the substrate projects into the waveguide filter.

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5. The waveguide filter as claimed in one of the preceding claims, characterized in that the substrate (S) has rear-face metallization (RM) on the lower face.
- 5 6. The waveguide filter as claimed in one of the preceding claims, characterized in that the component (FB) and the substrate (S) are conductively connected, in particular being soldered or conductively adhesively bonded.
- 10 7. The waveguide filter as claimed in one of the preceding claims, characterized in that the component (FB) has a conductive surface.
8. Use of a waveguide filter as claimed in one of the preceding claims in a transmitting/receiving
15 arrangement for a communication and/or radar application.

Waveguide filter

Abstract

The invention relates to a waveguide filter formed from a substrate (S), which is coated on the upper face with a structured metallic layer (TM) and one or more metallic striplines (ML1, ML2), and from a component (FB), with the component (FB) being fitted to the upper face of the substrate (S) and with one side wall of the waveguide filter being formed by the structured metallic layer (TM) of the substrate (S), and with the other side walls of the waveguide filter being formed by the component (FB), and with the waveguide filter having input and output points for coupling the electromagnetic waves carried in the stripline (ML1, ML2) to the waveguide filter, and vice versa.

(Figure 5)